ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES* in	Iaterial Composit Copyright 2005. IPC, E ternational and Pan-Am	ion Dec Bannockbu lerican cop	laration urn, Illinois. A pyright conver	ll rights reserved utions.	under both	This docume level parts, t	ent is a declar he declaration	ration o n encor	of the substances mpasses all lowe	within or level 1	the manufactunaterials for v	urer listed it which the m	em. No anufac	ote: if the turer has	e item is an as s engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information											
upplier Informatio	on																
Company name* Compa				any unique ID			Unique ID Authority					Respons	Response Date*				
nsemi												2024-05-	20				
Contact Name			Title - Contact				Phone - Contact*				Email -	Email - Contact*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product	Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative			Phone - Representative*				Email -	Email - Representative*						
roduct-Env-Stewards			Product Enviro Compliance				NA				Product	Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Iten		Mfr Item	Number Mfr Item Name				Effective Da	ate V	version	Manufacturing Site		N	Veight	*	UOM	Unit Type	
	NOIX5SN5000B-LTI XGS5N		XGS5MP, 4port,	P, 4port, Mono		2024-05-20			TA1		1	189.09)	mg	Each		
Ianufacturing Pro	ccess Information						·		L						1	I	
Terminal Plating / Grid Array Material Ter		erminal Base A	Alloy	J-STD-020 MSL Ratir		Peak Process		s Body Temperature N		Time at Peal	k Temperat	ure N	lumber o	of Reflow Cyc	les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Cl Sn)		U Alloy		4		245 C		30		secon	is 3	s 3					
omments																	
or more information re	garding material com	position p	lease refer to	page 3													

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Birective 2011/65/EU amending RoHS Birective 2011/65/EU B										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	220.55	mg		Misc.	proprietary data		0.8381	mg
			Supplier	Silicon (Si)	7440-21-3		217.5285	mg
			Supplier	Aluminum (Al)	7429-90-5		2.1834	mg
Die Attach Epoxy	45.39	mg	Supplier	2,2-bis(acryloyloxymethyl)butyl acrylate	15625-89-5		34.0425	mg
			Supplier	Imidazole Addition	68490-66-4		1.3617	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		6.8085	mg
			Supplier	Silica (SiO2)	14464-46-1		3.1773	mg
naging Lens	456.52	mg	Supplier	Sulfur (S)	7704-34-9		2.2826	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		22.826	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		22.826	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		22.826	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		22.826	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		22.826	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		22.826	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		317.2814	mg
Lid Attach	5.77	mg		Epoxy resin	proprietary data		4.6679	mg
			Supplier	Adeka Optomer SP 150	125054-47-9		0.1385	mg
			Supplier	Photoinitiator	Proprietary Data		0.427	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.5366	mg
Mold Compound-Black	256.37	mg		Phenolic Resin	proprietary data		38.4555	mg
			Supplier	Oxirane	39817-09-9		38.4555	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		7.6911	mg
			Supplier	Carbon Black (C)	1333-86-4		2.5637	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		164.0768	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5.1274	mg
Substrate	202.55	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		42.9406	mg
			Supplier	Inorganic filler	Proprietary Data		26.4935	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		2.6534	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.6482	mg
			Supplier	Acetophenone Derivative	Proprietary Data		3.97	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6684	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.6684	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	7.94	mg
			Supplier	Copper (Cu)	7440-50-8	96.0492	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	20.5183	mg
Wire Bond - Au	1.94	mg	Supplier	Gold (Au)	7440-57-5	1.94	mg